



DATA SHEET

CHIP Low Impedance 105°C

Serie: I15008

Voltage: 25Volt Range: 100 μ F

Impedance: 0,6 Ω Dimension 6,3x7,7mm

Ripple Current: 230mA

CHIP Low Impedance 105°C

Serie No.: I15008

Customer:

DRW:	Jason	CHKD	Wilson	MATL:	Wilson	TOLERANCE	Mason	DATE	03.06.2014
APPD:	Schumi			FINISH	Jamy		Sheet No.	1 from 7	

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Designed for surface mounting on high density circuit board
Emboss carrier tape packing systems is available for automatic insertion



Technical Informations

Voltage:	25Volt
Range;	100µF
Dimension; D x L mm	6,3x7,7mm
Impedance (Ω) max., at 20°C, 100kHz	0,6Ω
Ripple Current (mA rms) at 105°C, 100kHz	230mA

Ordering Code			
250	Voltage		
101	Range		
D=	C	L=	3

Low Impedance with Operating Temperatur Range of -55°C ~ +105°C
Load Life of 1000~2000hours

Leakage current max.	Ø4 ~ Ø10mm		I= 0,01CV or 3µA whichever is greater (after 2 minutes)										
	Ø12,5 ~ Ø16mm		I= 0,03CV or 4µA whichever is greater (after 1 minutes)										
Capacitance tolerance	± 20% at 120Hz, 20°C												
Dissipation factor max. (at 120Hz, 20°C)	WV		6,3	10	16	25	35	50					
	Tanδ	Ø4 ~ Ø10mm	0,22	0,19	0,16	0,14	0,12	0,12					
		Ø12,5 ~ Ø16mm	0,26	0,22	0,18	0,16	0,14	0,12					

Low Temperatur characteristics (Impedance ratio at 120Hz)	WV		6,3	10	16	25	35	50						
	Ø4 ~ Ø10mm	Z-25°C / Z+20°C	2	2	2	2	2	2						
		Z-55°C / Z+20°C	5	4	4	3	3	3						
	Ø12,5 ~ Ø16mm	Z-25°C / Z+20°C	3	3	2	2	2	2						
		Z-55°C / Z+20°C	10	8	6	4	3	3						

Load Life (after aplication of the rated voltage for 2000hrs at 105°C	Leakagge current	Less than specified value
	Capacitance Change	Within ±20% of initial value
	Tanδ	Less than 200% of specified value
	Ø4 ~ Ø6,3x5,4: 1000hours	

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Shell life (at 105°C)	After 1000hours no load test, leakage current, capacitance and $\tan\delta$ are same as load life value.
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Resistance to soldering heat	After reflow soldering and resistance at room temperature, they meet the characteristics requirements listed at underside	
	Leakage current	Less than specified value
	Capacitance Change	Within $\pm 10\%$ of initial value
	$\tan\delta$	Less than specified value

Size	FREQUENCY COEFFICIENT OF PERMISSIBLE RIPPLE CURRENT						
	Capacitance	Frequency					
	μF	50Hz	120Hz	300Hz	1KHz	10KHz $\leq$	
Ø4 ~ Ø10mm	1,0~ 68	0,35	0,50	0,64	0,83	1,00	
	100~2200	0,40	0,55	0,70	0,85	1,00	
Ø12,5 ~ Ø16mm	~680	0,45	0,65	0,80	0,90	1,00	
	1000 ~4700	0,65	0,85	0,95	1,00	1,00	

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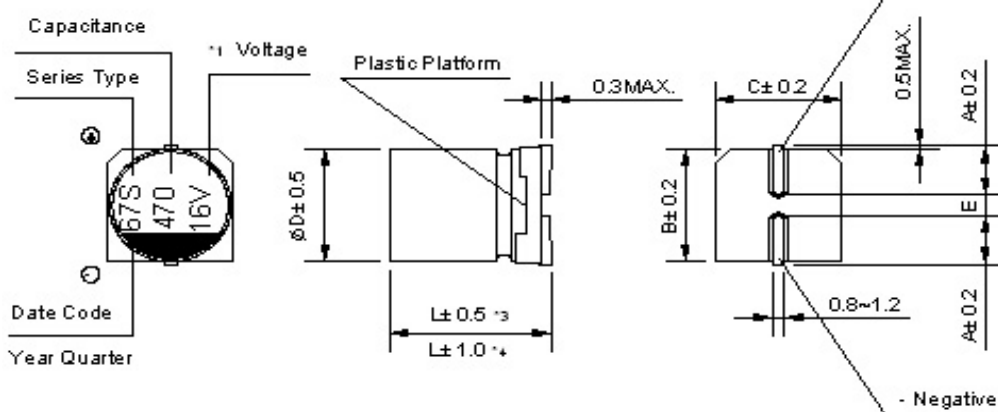
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Technical Drawing

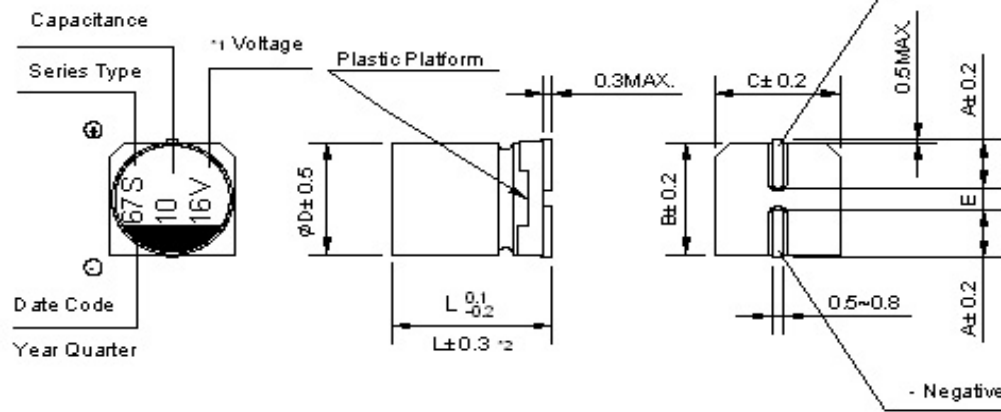
Dimension of Size Ø 8x10,5 ~ 16mm

(Ø 8x10,5~Ø 16)



Dimension of Size Ø 4~ 8x6,2mm

(Ø 4~Ø 8x6.2)



D x L	Ø 4 x 5,4	Ø 5 x 5,4	Ø 6,3 x 5,4	Ø 6,3 x 7,7	Ø 8 x 6,2	Ø 8 x 10,5	Ø 10 x 10,5	Ø 10 x 13,5	Ø 12,5 x 13,5	Ø 12,5 x 16	Ø 16 x 16,5
A	2,0	2,2	2,6	2,6	3,4	3,0	3,3	3,3	4,9	4,9	5,8
B	4,3	5,3	6,6	6,6	8,4	8,4	10,4	10,4	13,0	13,0	17,0
C	4,3	5,3	6,6	6,6	8,4	8,4	10,4	10,4	13,0	13,0	17,0
E +/-0.2	1,0	1,3	1,9	1,9	2,3	3,1	4,7	4,7	4,7	4,7	6,4
L	5,4	5,4	5,4	7,7	6,2	10,5	10,5	13,5	13,5	16,0	16,5

*1 Voltage mark (6V) represents 6,3V for Ø 4 ~ 10mm

*3 (L +/- 0.5) is applicable to Ø 8x10,5 ~ Ø 10mm

*2 (L +/- 0.3) is applicable to Ø 6,3 ~ 7.7 and Ø 8 + 6,2mm

*4 (L +/- 1.0) is applicable to Ø 12,5 ~ Ø 16mm

RE. Date code and series type -1st digit for Year 2nd digit for Quarter, 4 quarter codes in one year area 1,4,7,0

3rd character for Series S

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[illegible]

Diameter ordering Code D	Code
3mm	3
4mm	A
5mm	B
6,3mm	C
8mm	E
10mm	G
12,5mm	I
16mm	K

Height ordering Code L	Code
4mm	A
5,4mm	0
5,8mm	1
6,2mm	2
7,7mm	3
10,5mm	4
13,5mm	5
16mm	6
16,5mm	7

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Ordering Informations

Serie	Voltage Code	Tolerance Code	Range Code	Size Code D	Size Code L	Special function	ROHS	Packing Code		
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I15008	250	M	101	C	3	XX	R	TR		
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look table Voltage Code	M= ±20%	Ordering Code Range	Look table Code D	Look table Code L	XX= No function	R= ROHS Conform N= NON ROHS Conform	TR= Tape Reel Packing BU= Bulk- Ware		
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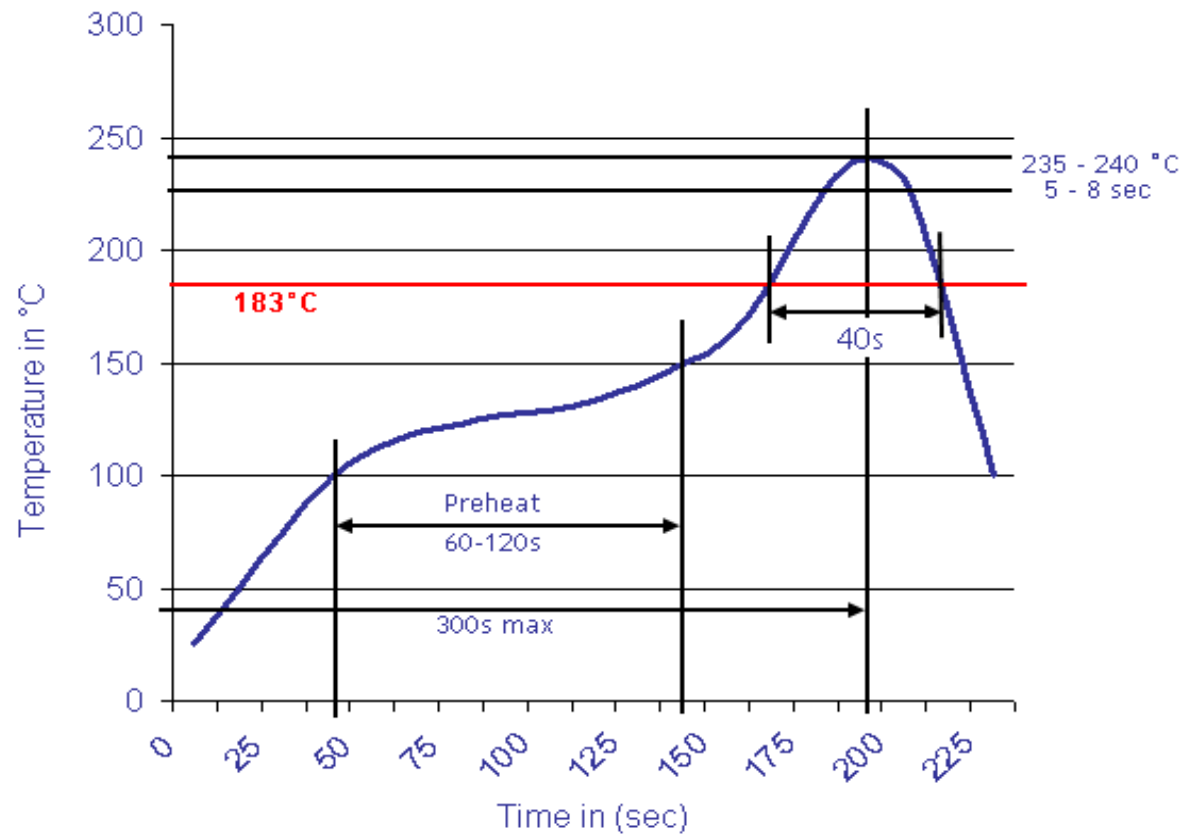


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Soldering Profile Curve

Classification Reflow Profile (JEDEC J-STD-020C)



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